



Material Content Data Sheet



Sales Product Name		BTS5016-1EKB		Issued		9. January 2019		
MA#		MA001594190						
Package		PG-DSO-14-47		Weight*		150.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.081	2.05	2.05	20471	20471
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		460	
	non noble metal	iron	7439-89-6	1.383	0.92		9193	
wire	non noble metal	copper	7440-50-8	56.175	37.33	38.31	373278	383046
	non noble metal	copper	7440-50-8	0.560	0.37	0.37	3724	3724
	encapsulation	organic material	carbon black	1333-86-4	0.169	0.11		1121
encapsulation	plastics	epoxy resin	-	7.758	5.16		51551	
	inorganic material	silicondioxide	60676-86-0	76.398	50.76	56.03	507660	560332
leadfinish	non noble metal	tin	7440-31-5	2.472	1.64	1.64	16424	16424
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9770	9770
glue	plastics	epoxy resin	-	0.164	0.11		1091	
	noble metal	silver	7440-22-4	0.774	0.51	0.62	5142	6233
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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